



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DB4X313K

Silicon epitaxial planar type

For small current rectification

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4J

■ Basic Part Number

Dual DB2J313 (Parallel)

■ Packaging

DB4X313K0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	Single	200	mA
	Double *1	130	
Peak forward current	Single	300	mA
	Double *1	220	
Non-repetitive peak forward surge current *2	Single	1.0	A
	Double *1	0.7	
Junction temperature	T_j	125	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Value of each diode in double diodes used.

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

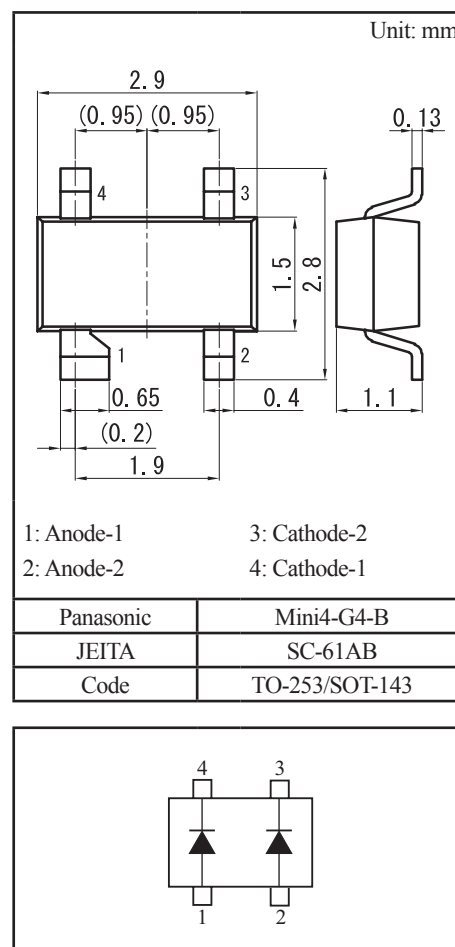
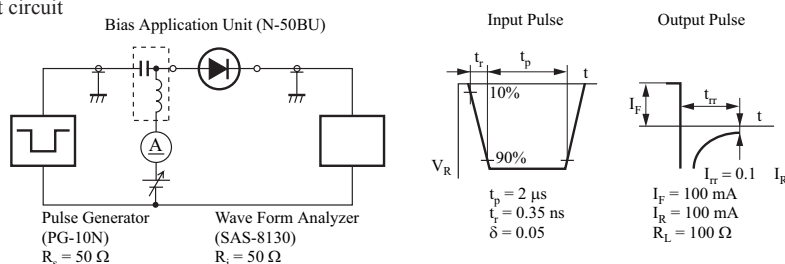
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μA
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *1	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{tr} = 0.1 \times I_R, R_L = 100 \Omega$		1.5		ns

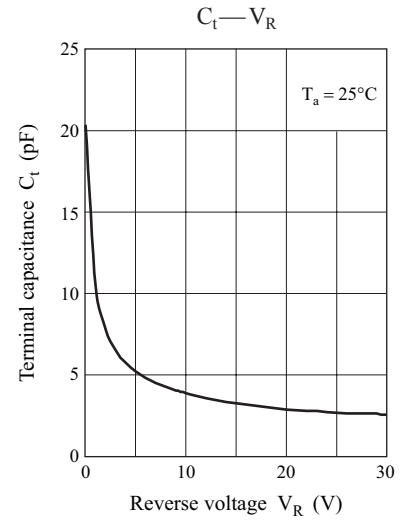
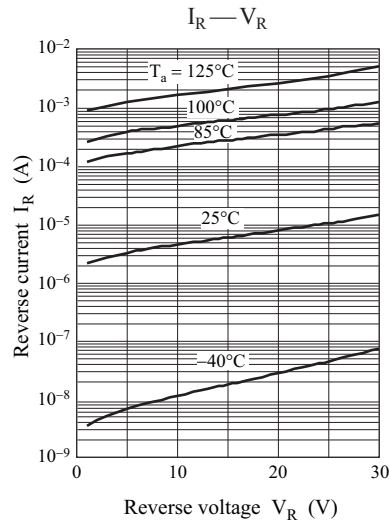
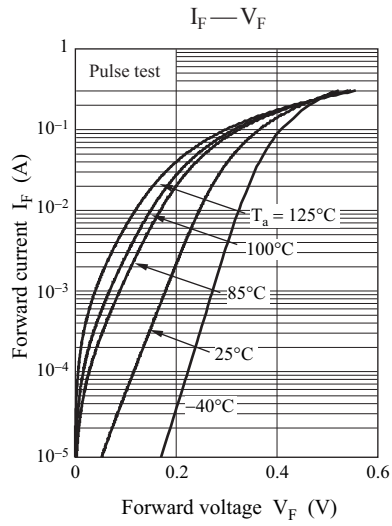
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 1 GHz

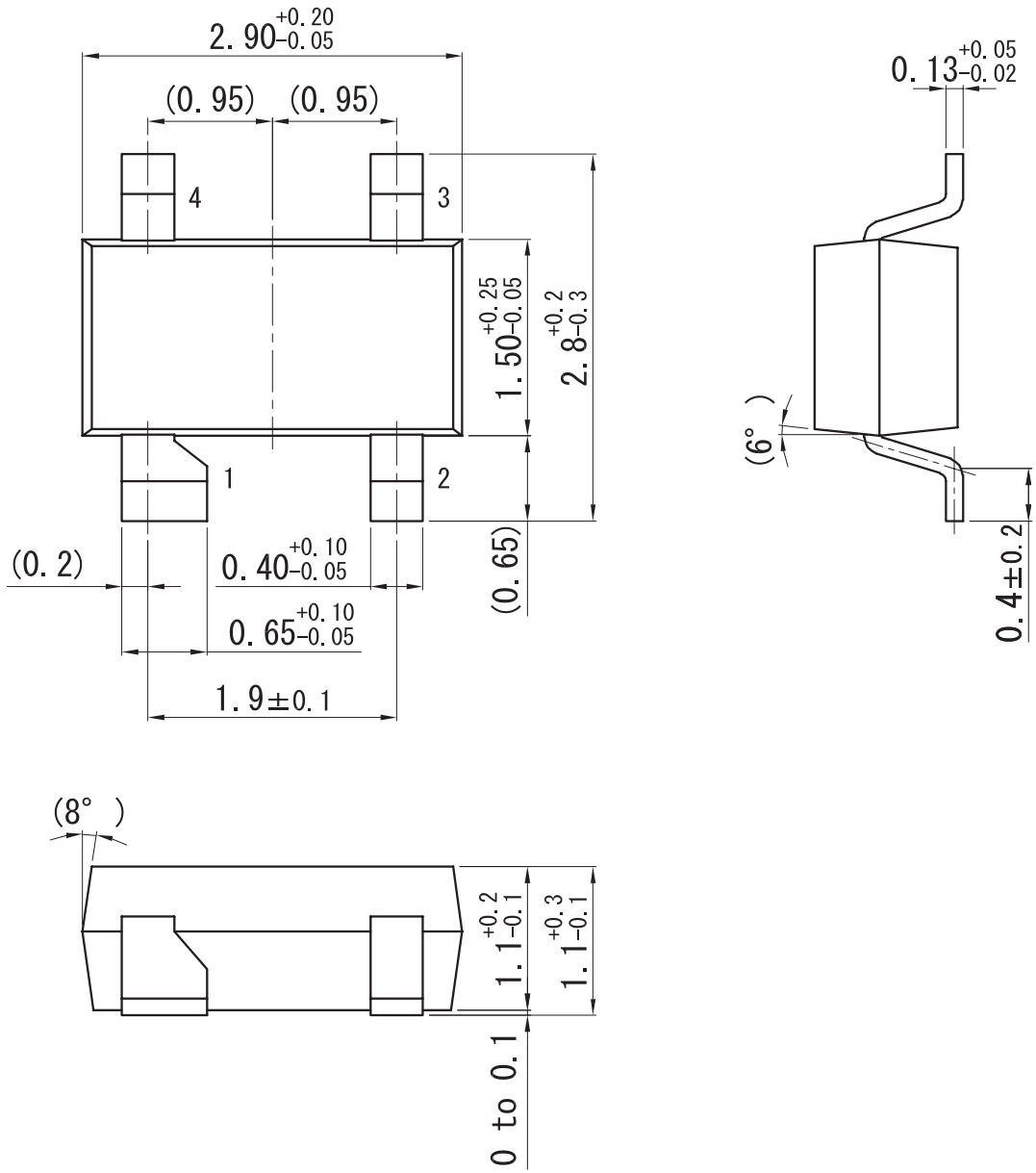
4. *1: t_{rr} measurement circuit



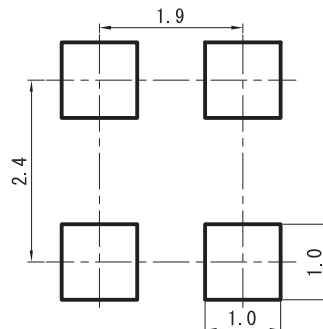


Mini4-G4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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